## Thermal and Plasma Enhanced Atomic Layer Deposition of TiO<sub>2</sub> from Amide and Alkoxide Precursors: Growth Characteristics and Photoelectrochemical Performance.

S.O'Donnell,<sup>a</sup> F.Jose,<sup>a</sup> K.Shiel,<sup>a</sup> M.Snelgrove,<sup>a</sup> C.McFeely,<sup>a</sup> R.O'Connor,<sup>a</sup>

<sup>*a*</sup> School of Physical Sciences, Dublin City University, Dublin 9, Ireland. <sup>+</sup> Author for correspondence: <u>shane.odonnell42@mail.dcu.ie</u>



## **Accompanying Abstract Figures**

Figure 1: XPS core level signal evolution increasing number of ALD Ti cycles, from 0 to 65 cycles, depicting the change in composition as the thickness of the titanium overlayer increases during TDMAT thermal growth. (a) Evolution of the O1s photoemission peak as it changes from a SiO<sub>2</sub> dominant peak TiO<sub>2</sub> dominant (b) Attenuation of the SiO<sub>2</sub> peak is shown (c) Ti2p region showing peak intensity increase with increasing cycles (d) C1s peak showing remnant carbon incorporation in the film.



Figure 2: Voltammetry measured photocurrent vs 1.23 V RHE as a function of sample treatment stage.